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Workflow for Authors - 2023

Background

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- ▶ 2) During the submission process, the corresponding author shall enter the school email address and/or the institution data , as it will be used to match the author with an institutional OA account.
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* <https://open.ieee.org/about/>

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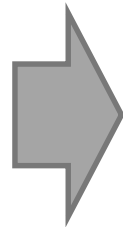
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Step 2 Post acceptance



IEEE Electronic Copyright Form



Step 4 Pay OA APC in TWD

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Step 3 RightsLink for Scientific Communications (RLSC)



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- 2020 IEEE International Electron Devices Meeting (IEDM)
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- Step 4: Authors & Institutions
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- Step 6: Review & Submit

Step 1: Type, Title, & Abstract

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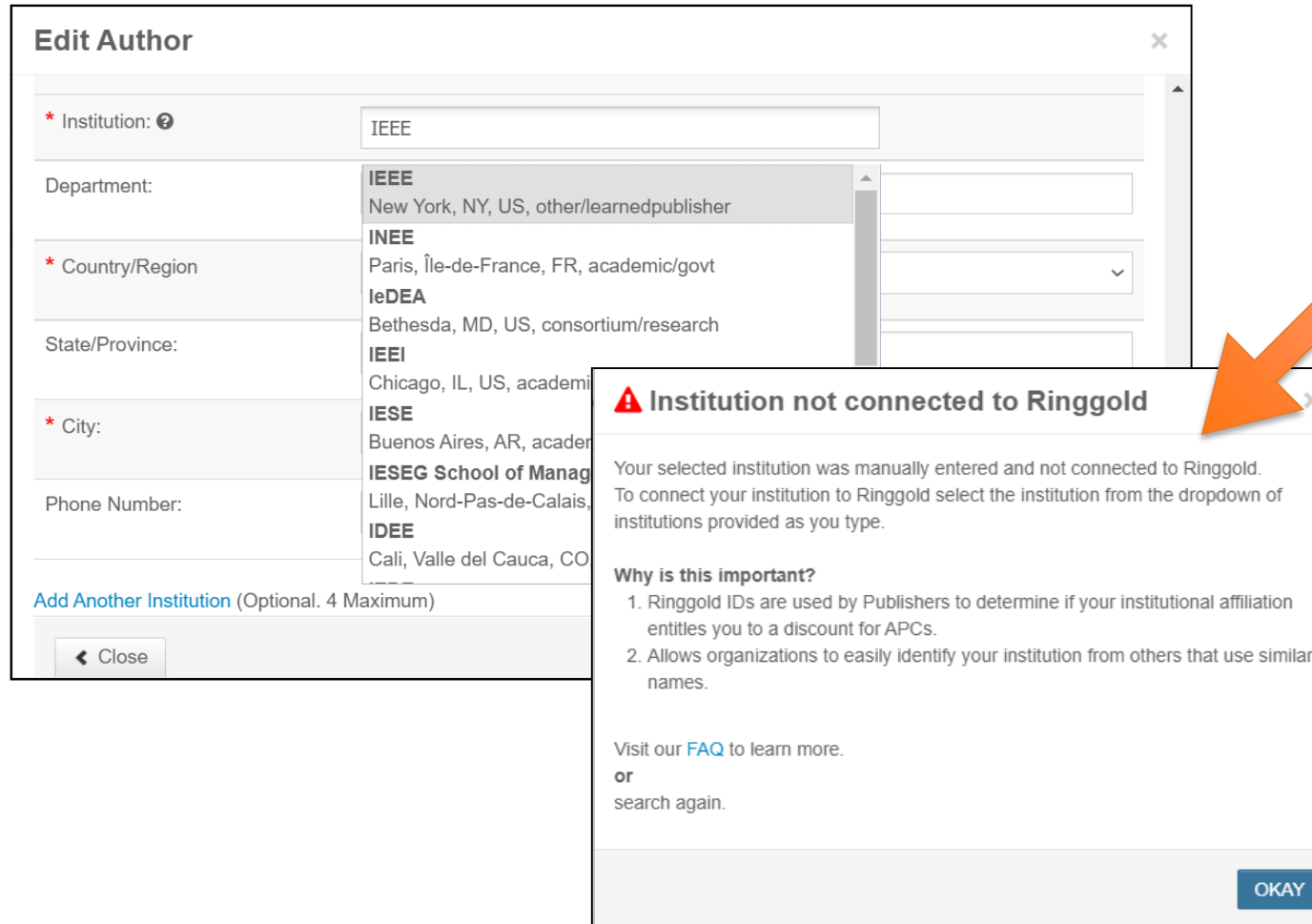
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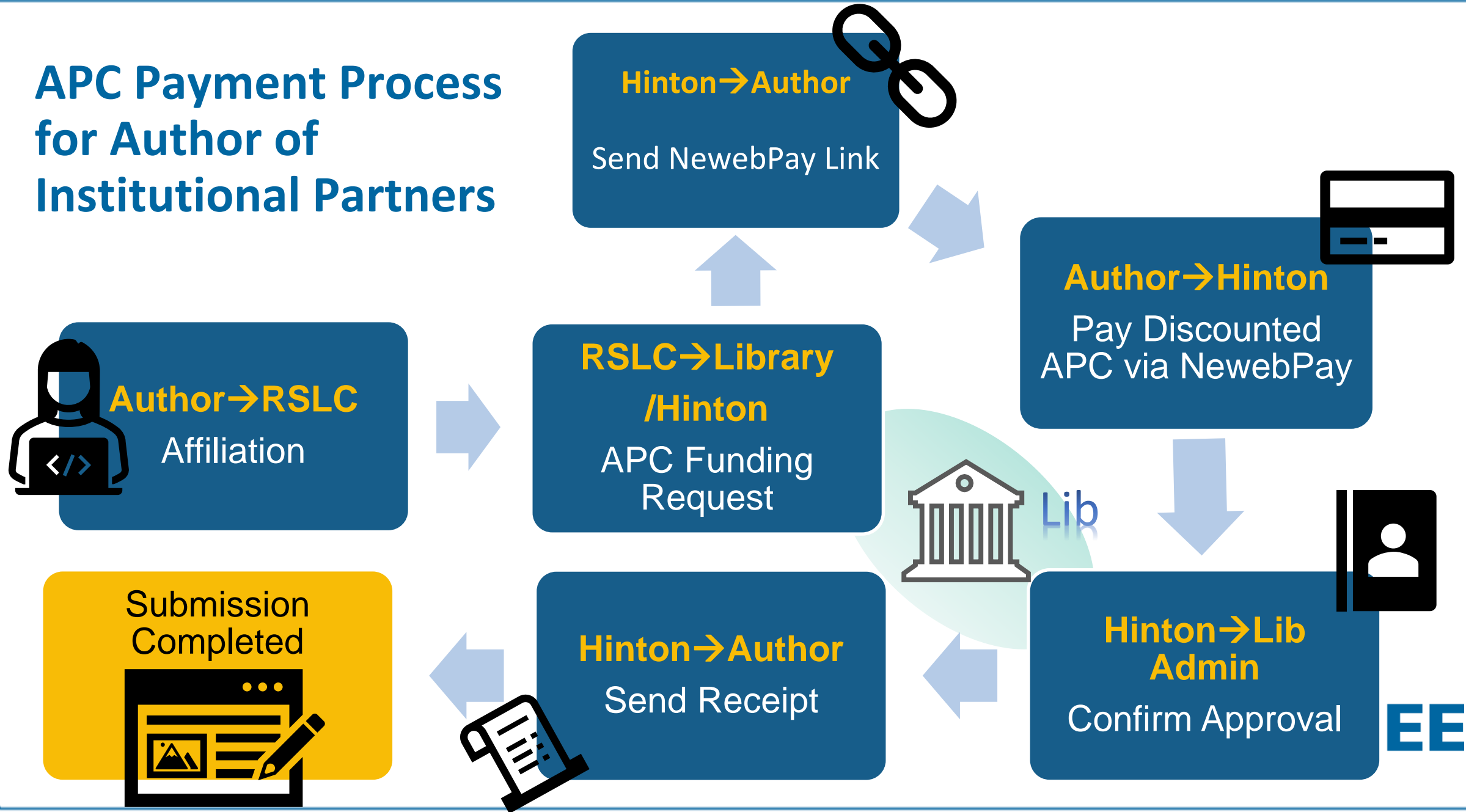
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